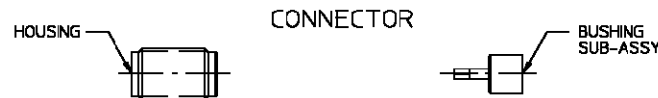


CONNECTOR TYPE	CABLE TYPE	TOOLS REQ'D
OS-2.9 PANEL FEEDTHROUGH JACK RECEPTACLE, FIELD REPLACEABLE	N/A	SOLDER FIXTURE: 2598-5285-54, 2598-5047-54 TORQUE KIT: 2598-5288-54 STEP DRILL: 2598-5286-54, 2598-5292-54 TAPPING DRILL: 2598-5287-54 SOLDER: INDALLOY #2 FLUX: KESTER #197 CLEANING FLUID: ISOPROPYL ALCOHOL



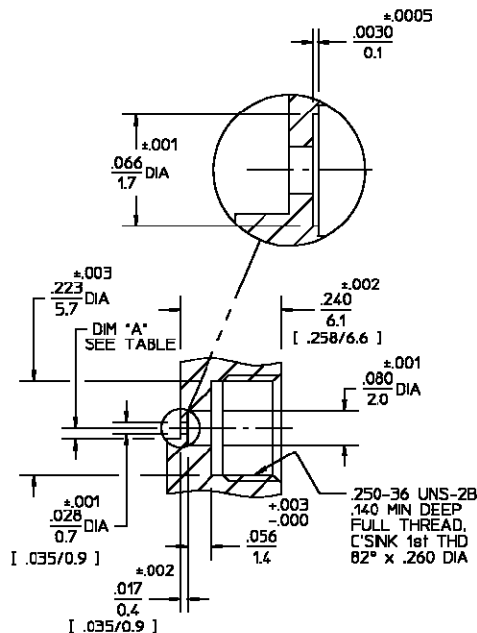
### ASSEMBLY OPERATIONS

- 1.0 MOUNTING HOLE PREPARATION
- 1.1 USING THE STEP DRILL, P/N 2598-5286-54 (2598-5292-54 FOR STRESS RELIEF CONTACT APPLICATIONS), REAM MOUNTING HOLE TO DEPTH SHOWN.
  - 1.2 TAP A .250-36 UNS-2B THREAD TO DEPTH SHOWN.
  - 1.3 CLEAN WITH SOLVENT.

#### RECOMMENDED DIMENSIONS FOR BOARD THICKNESS VARIATIONS

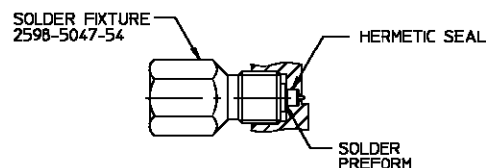
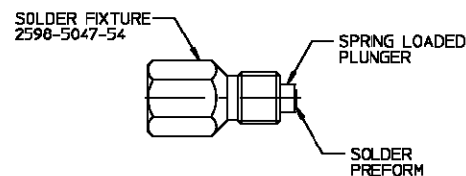
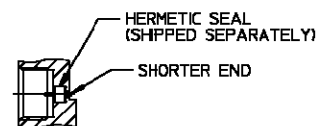
BOARD THICKNESS	DIM "A" ± .001
.010	.019
.015	.024
.020	.029
.025	.034

- NOTES:
1. DIA'S CONCENTRIC WITHIN .002 TIR
  2. DIMENSIONS ARE IN IN/(MM)
  3. DIMENSIONS IN BRACKETS APPLY IF STRESS RELIEF CONTACTS ARE USED.



#### OPTION 1

- 2.0 INSTALLATION OF HERMETIC SEAL
- 2.1 CLEAN HERMETIC SEAL IN ISOPROPYL ALCOHOL.
  - 2.2 APPLY FLUX TO THE OUTER CONDUCTOR OF THE HERMETIC SEAL. CARE SHOULD BE TAKEN TO AVOID GETTING FLUX ON THE CENTER PIN.
  - 2.3 INSERT SEAL INTO THE MOUNTING HOLE WITH THE SHORT PIN END TOWARDS THE .028±.001 DIA HOLE. SUCH THAT THE PIN EXTENDS THROUGH THE PANEL AS SHOWN.
  - 2.4 PLACE A RING OF SOLDER ON THE LIP OF THE SOLDER FIXTURE PLUNGER AS SHOWN.
  - 2.5 SCREW THE SOLDER FIXTURE INTO THE MOUNTING HOLE AS SHOWN.
  - 2.6 HEAT THE PANEL TO ALLOW SOLDER TO FLOW. NOTE: INDALLOY #2 SOLDER FLOWS AT 149°C.
  - 2.7 REMOVE FROM HEAT SOURCE AND ALLOW TO FULLY COOL.
  - 2.8 ATTACH THE CENTER CONDUCTOR OF THE GLASS SEAL TO THE MICROSTRIP.
  - 2.9 UNSCREW SOLDER FIXTURE AND CLEAN SOLDERED AREA WITH SOLVENT.

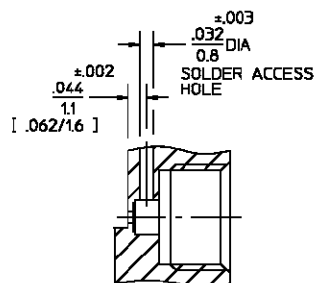


## OPTION 2

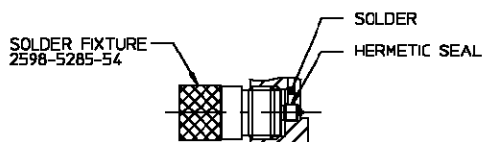
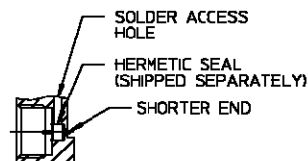
- 1.0 MOUNTING HOLE PREPARATION  
SAME AS OPTION 1 WITH THE ADDITION OF  
THE SOLDER ACCESS HOLE AS SHOWN.

## NOTES:

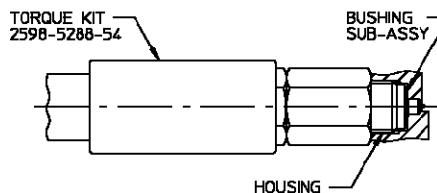
1. DIMENSIONS ARE IN IN/(MM).
2. DIMENSIONS IN BRACKETS APPLY IF  
STRESS RELIEF CONTACTS ARE USED.



- 2.0 INSTALLATION OF HERMETIC SEAL
- 2.1 CLEAN HERMETIC SEAL IN ISOPROPYL ALCOHOL.
  - 2.2 APPLY FLUX TO THE OUTER CONDUCTOR OF THE HERMETIC SEAL. CARE SHOULD BE TAKEN TO AVOID GETTING FLUX ON THE CENTER PIN.
  - 2.3 INSERT SEAL INTO THE MOUNTING HOLE WITH THE SHORT PIN END TOWARDS THE .028±.001 DIA HOLE, SUCH THAT THE PIN EXTENDS THROUGH THE PANEL AS SHOWN.
  - 2.4 SCREW THE SOLDER FIXTURE INTO THE MOUNTING HOLE AS SHOWN, TO HOLD HERMETIC SEAL IN PLACE.
  - 2.5 INSERT SOLDER INTO THE SOLDER ACCESS HOLE.
  - 2.6 HEAT THE PANEL TO ALLOW SOLDER TO FLOW. NOTE: INDALLOY #2 SOLDER FLOWS AT 149° C.
  - 2.7 REMOVE FROM HEAT SOURCE AND ALLOW TO FULLY COOL.
  - 2.8 ATTACH THE CENTER CONDUCTOR OF THE GLASS SEAL TO THE MICROSTRIP.
  - 2.9 UNSCREW SOLDER FIXTURE AND CLEAN SOLDERED AREA WITH SOLVENT.



- 3.0 INSTALLATION OF THE CONNECTOR ASSY ONTO THE PANEL
- 3.1 ASSEMBLE BUSHING SUB-ASSY INTO REAR OF HOUSING.
  - 3.2 THREAD THE CONNECTOR INTO THE PANEL MOUNTING HOLE AS SHOWN, BEING SURE THAT THE HERMETIC SEAL PIN ENTERS THE CENTER CONTACT OF THE CONNECTOR.
  - 3.3 TORQUE THE CONNECTOR TO 16 IN-LBS USING THE FEMALE TORQUE DRIVER (REF P/N 2598-5288-54).



## \*\*\* CAUTION \*\*\*

AVOID CLEANING FLUIDS CONTAINING HALOGENATED AND AROMATIC HYDROCARBONS (FREON □). THESE COMPOUNDS MAY SOFTEN OR DISSOLVE THE PP0 ■ BEAD MATERIAL IN THE SUPPORT BEAD INSIDE THE BUSHING SUB-ASSEMBLY

- - TRADEMARK OF DuPONT CORP  
■ - TRADEMARK OF GENERAL ELECTRIC